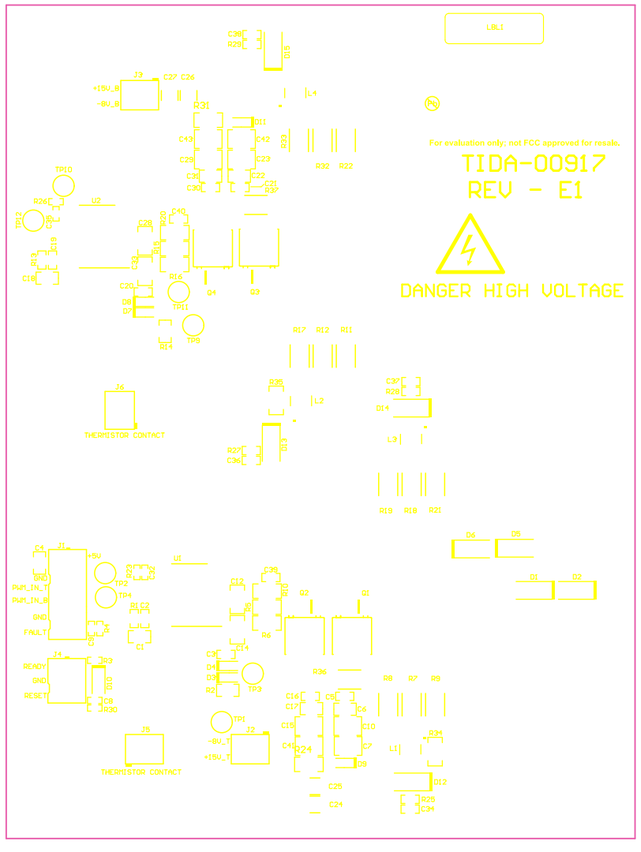
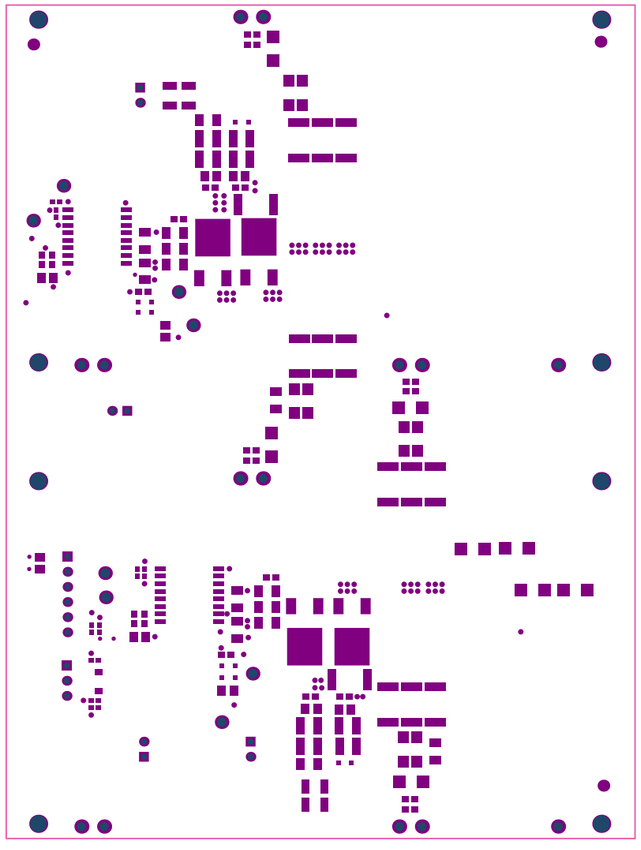



| | | | |
|---|---|---|---|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-00917 | REV: E1 | SVN REV: Not In VersionControl |
| LAYER NAME = Top Overlay | TID #: 00917 | | |
| PLOT NAME = Top Overlay | GENERATED : 11/25/2016 11:56:25 AM | | TEXAS INSTRUMENTS |



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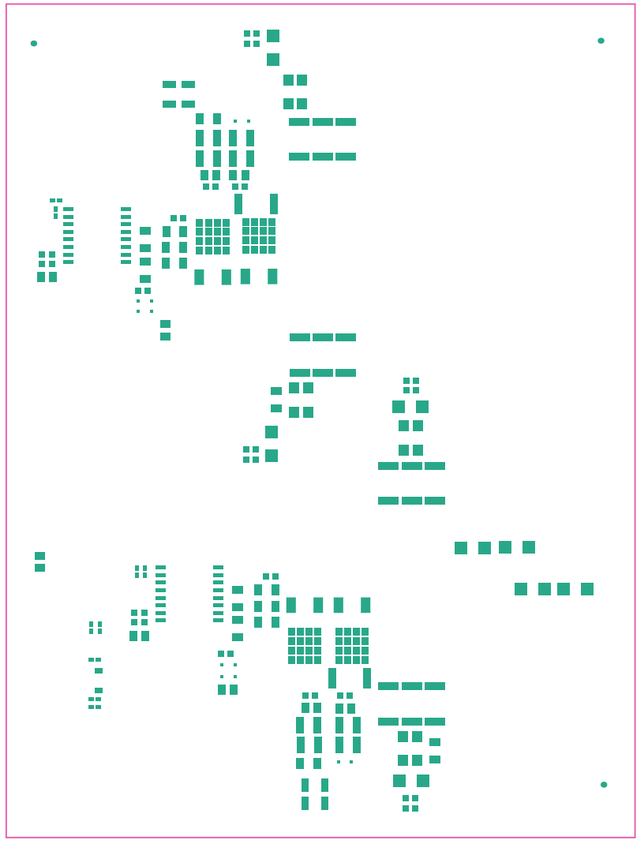
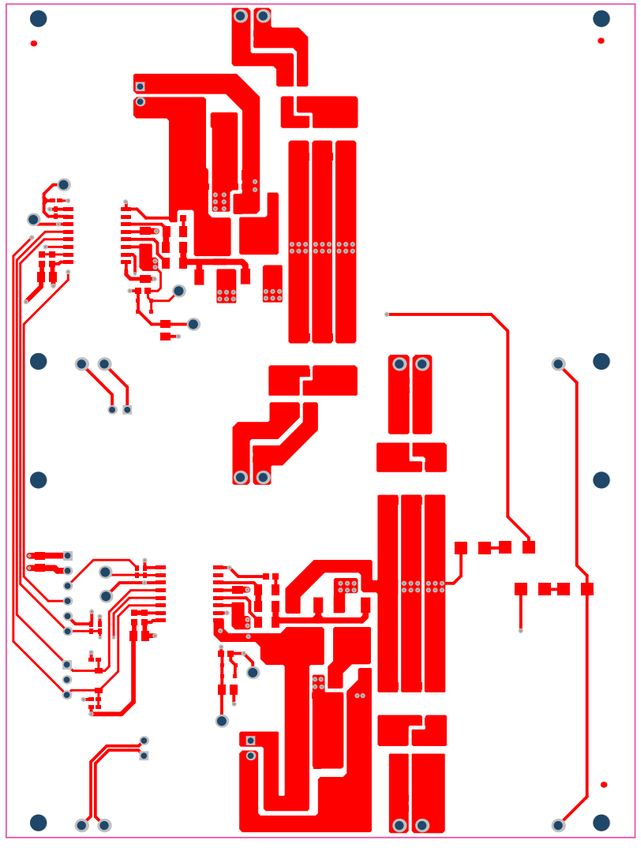
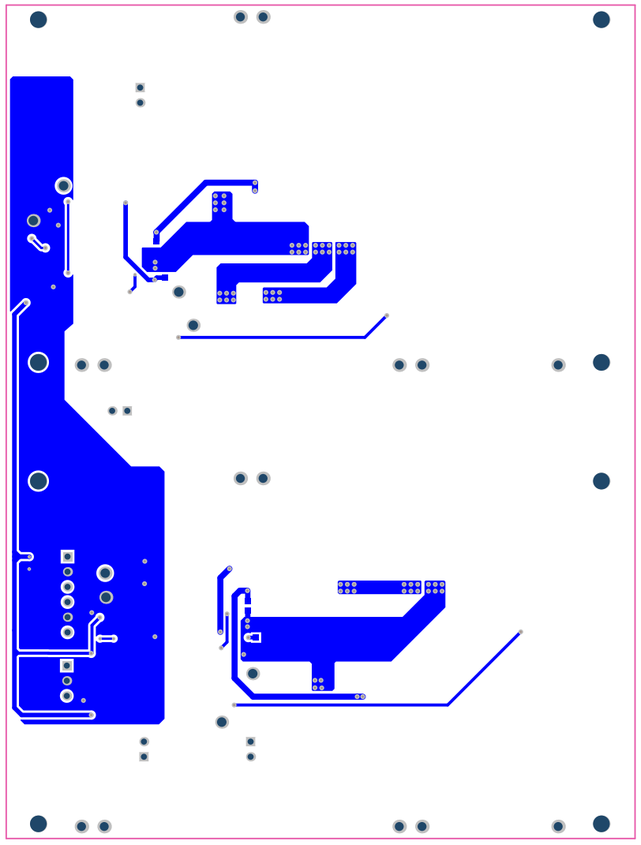
|---|---|---|---|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-00917 | REV: E1 | SVN REV: Not In VersionControl |
| LAYER NAME = Top Solder | TID #: 00917 | | |
| PLOT NAME = Top Solder Mask | GENERATED : 11/25/2016 11:56:26 AM | | TEXAS INSTRUMENTS |



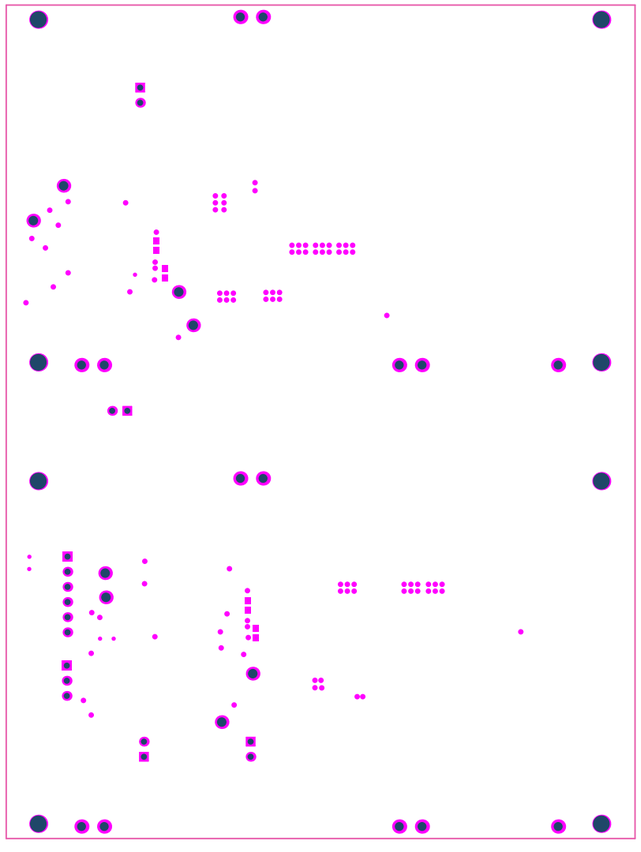
| | | | |
|---|---|---|---|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-00917 | REV: E1 | SVN REV: Not In VersionControl |
| LAYER NAME = Top Paste | TID #: 00917 | | |
| PLOT NAME = Top Paste | GENERATED : 11/25/2016 11:56:26 AM | | TEXAS INSTRUMENTS |



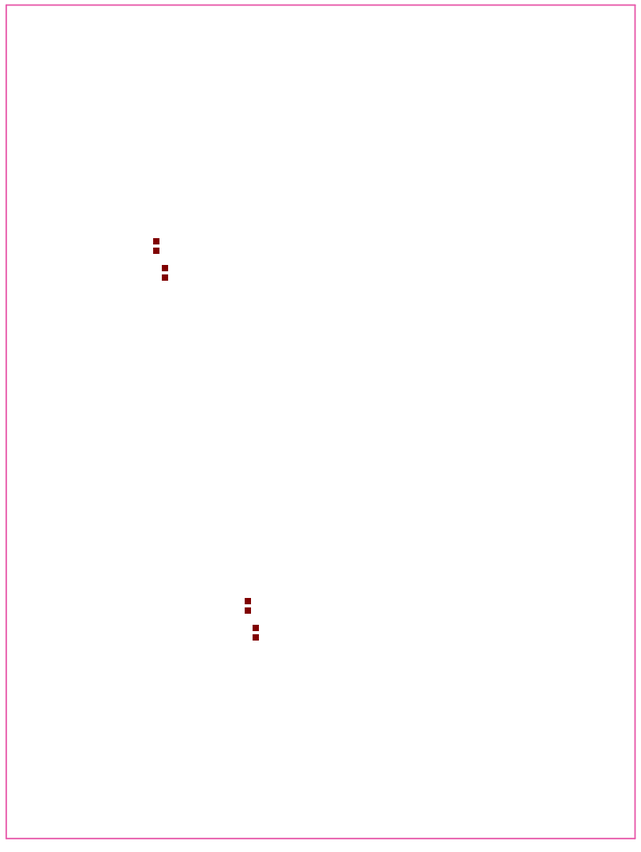
| | | | |
|---|---|---|---|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-00917 | REV: E1 | SVN REV: Not In VersionControl |
| LAYER NAME = Top Layer | TID #: 00917 | | |
| PLOT NAME = Top Layer | GENERATED : 11/25/2016 11:56:27 AM | | TEXAS INSTRUMENTS |



| | | | |
|---|---|---|---|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-00917 | REV: E1 | SVN REV: Not In VersionControl |
| LAYER NAME = Bottom Layer | TID #: 00917 | | |
| PLOT NAME = Bottom Layer | GENERATED : 11/25/2016 11:56:28 AM | | TEXAS INSTRUMENTS |



| | | | |
|---|---|---|---|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-00917 | REV: E1 | SVN REV: Not In VersionControl |
| LAYER NAME = Bottom Solder | TID #: 00917 | | |
| PLOT NAME = Bottom Solder Mask | GENERATED : 11/25/2016 11:56:28 AM | | TEXAS INSTRUMENTS |



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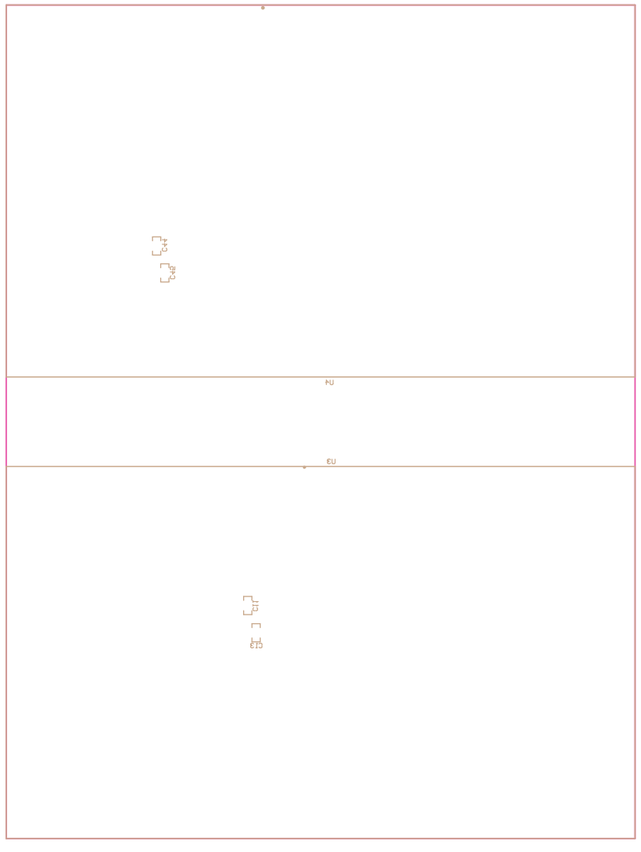
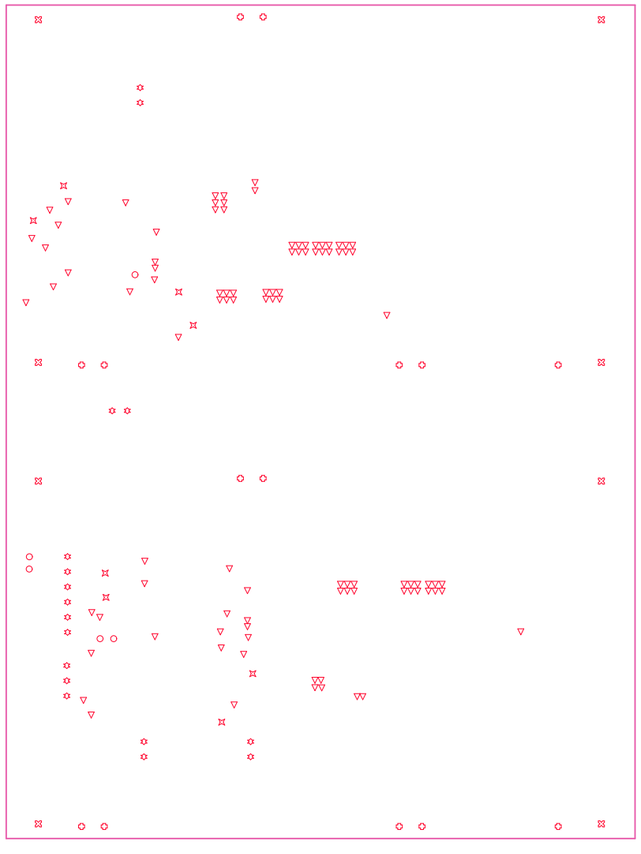
|---|---|---|---|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-00917 | REV: E1 | SVN REV: Not In VersionControl |
| LAYER NAME = Bottom Paste | TID #: 00917 | | |
| PLOT NAME = Bottom Paste | GENERATED : 11/25/2016 11:56:29 AM | | TEXAS INSTRUMENTS |



| | | | |
|---|---|---|---|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-00917 | REV: E1 | SVN REV: Not In VersionControl |
| LAYER NAME = Bottom Overlay | TID #: 00917 | | |
| PLOT NAME = Bottom Overlay | GENERATED : 11/25/2016 11:56:30 AM | | TEXAS INSTRUMENTS |



| Symbol | Hit Count | Tool Size | Plated | Hole Type |
|---|---|---|---|---|
| ○ | 5 | 12mil (0.305mm) | PTH | Round |
| ▽ | 97 | 16mil (0.406mm) | PTH | Round |
| ☼ | 17 | 40.157mil (1.02mm) | PTH | Round |
| ◌ | 14 | 59.055mil (1.5mm) | PTH | Round |
| ⌑ | 8 | 63mil (1.6mm) | PTH | Round |
| ⊠ | 8 | 110.236mil (2.8mm) | NPTH | Round |
| | 149 Total | | | |

Drill Table
FOR 12MIL DRILL +0/-12MIL
FOR 16MIL DRILL +0/-16MIL
FOR PTH DRILL +/-3MIL
FOR NPTH DRILL +/-2MIL

**Layer Stack Up Detail for: TIDA-00917-E1.Pcbdoc**

| Layer Name | Gerber Document | Copper Thickness | Dielectric Material |
|---|---|---|---|
| Top Solder Mask | (.GTS) | | Solder Resist |
| Top Layer | (.GTL) | 1.4mil | FR4-High Tg |
| Bottom Layer | (.GBL) | 1.4mil | FR4-High Tg |
| Bottom Solder Mask | (.GBS) | | Solder Resist |

**DESIGN INFORMATION**

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
105.54MM X 139.84MM

Number of Layers : 2
MIN. TRACK WIDTH: 15 MIL
MIN. CLEARANCE: 8 MIL
MIN. VIA DRILL SIZE: 12 MIL
MINIMUM ANNULAR RING 6 MIL ( 0.1524 mm) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 63 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
COPPER THICKNESS (FINISHED):
OUTER: [X] 1.4MIL (1oz) [ ] 2MIL (1.4oz) [ ] 2.8MIL (2oz)
INNER SIGNAL: [ ] 1.4MIL (1oz) [ ] 2.8MIL (2oz) [X] N/A
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS: VIA TENTING: YES [ ] NO [X]
MICROSECTION: [ ] YES IMPEDANCE CONTROL: YES [ ] NO [X]
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

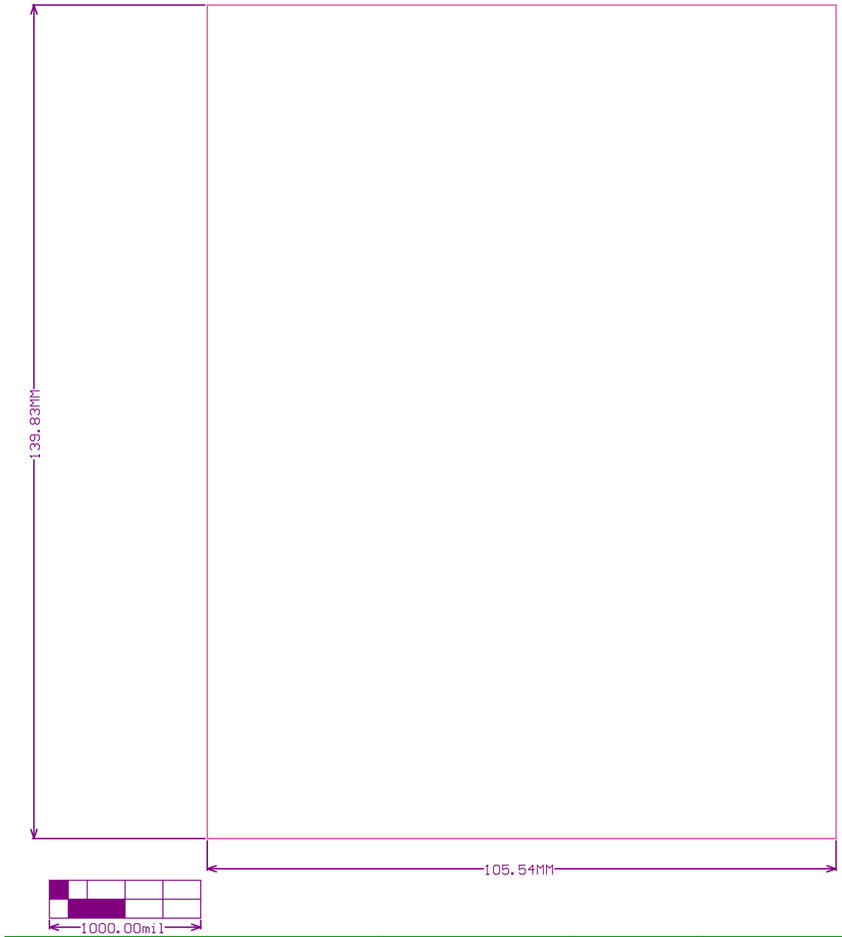
TEXAS INSTRUMENTS

PROJECT TITLE: TIDA-00917
DESIGNED FOR: Public Release
FILE NAME: TIDA-00917.PcbDoc

| | | | |
|---|---|---|---|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-00917 | REV: E1 | SVN REV: Not In VersionControl |
| LAYER NAME = Drill Drawing | TID #: 00917 | | |
| PLOT NAME = Drill Drawing | GENERATED : 11/25/2016 11:56:30 AM | | TEXAS INSTRUMENTS |



| | |
|---|---|
| ENGINEER: AB/PN | LAYOUT BY: Avinash N |
| SCALE: 1.00 | ALTIUM DESIGNER VERSION: 16.1.9.221 |




| | | | |
|---|---|---|---|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-00917 | REV: E1 | SVN REV: Not In VersionControl |
| LAYER NAME = | TID #: 00917 | | |
| PLOT NAME = Board Dimensions | GENERATED : 11/25/2016 11:56:32 AM | | TEXAS INSTRUMENTS |

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